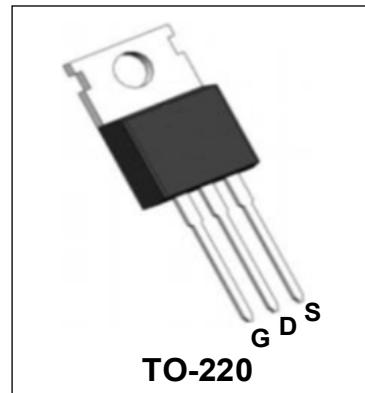


## 85V N-Channel Enhancement Mode Power MOSFET

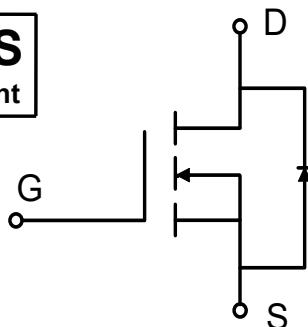
### Description

WMK053NV8HGS uses Wayon's advanced power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.



### Features

- $V_{DS} = 85V$ ,  $I_D = 125A$ (Silicon Limited)
- $R_{DS(on)} < 5.5m\Omega$  @  $V_{GS} = 10V$
- High Speed Power Switching
- Low Gate Charge
- Low  $R_{DS(ON)}$
- 100% EAS Guaranteed



### Applications

- Battery Management System
- Power Management Switching
- Motor Drive

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	85	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup> (Silicon Limited)	$I_D$	125	A
		79	
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	500	A
Single Pulse Avalanche Energy <sup>3</sup>	<b>EAS</b>	370	mJ
Total Power Dissipation <sup>4</sup>	$P_D$	162	W
Operating Junction and Storage Temperature Range	$T_J$ , $T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	58	°C/W
Thermal Resistance from Junction-to-Lead <sup>1</sup>	$R_{\theta JC}$	0.77	°C/W

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	85	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$ $T_J=100^\circ\text{C}$	$I_{DSS}$	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1	$\mu\text{A}$
			-	-	100	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	4	V
Drain-Source on-Resistance <sup>2</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	4.7	5.5	$\text{m}\Omega$
Forward Transconductance <sup>2</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 20 A$	-	57.8	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 40V, V_{GS} = 0V, f = 1\text{MHz}$	-	4645	-	$\text{pF}$
Output Capacitance	$C_{oss}$		-	673	-	
Reverse Transfer Capacitance	$C_{rss}$		-	41	-	
<b>Switching Characteristics</b>						
Gate Resistance	$R_g$	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	-	1.8	-	$\Omega$
Total Gate Charge	$Q_g$	$V_{GS} = 10V, V_{DS} = 40V, I_D = 50A$	-	61.3	-	$\text{nC}$
Gate-Source Charge	$Q_{gs}$		-	21	-	
Gate-Drain Charge	$Q_{gd}$		-	11	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DS} = 40V, R_G = 3\Omega, I_D = 50A$	-	16.5	-	$\text{ns}$
Rise Time	$t_r$		-	51.8	-	
Turn-off Delay Time	$t_{d(off)}$		-	37.1	-	
Fall Time	$t_f$		-	8.2	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$I_S = 50A, V_{GS} = 0V$	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G = V_D = 0V, \text{Force Current}$	-	-	125	A
Reverse Recovery Time <sup>2</sup>	$t_{rr}$	$I_F = I_S, dI/dt = 100A/\mu\text{s}$	-	69	-	$\text{ns}$
Reverse Recovery Charge <sup>2</sup>	$Q_{rr}$		-	141	-	$\text{nC}$

## Notes:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.4\text{mH}, I_{AS}=43A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

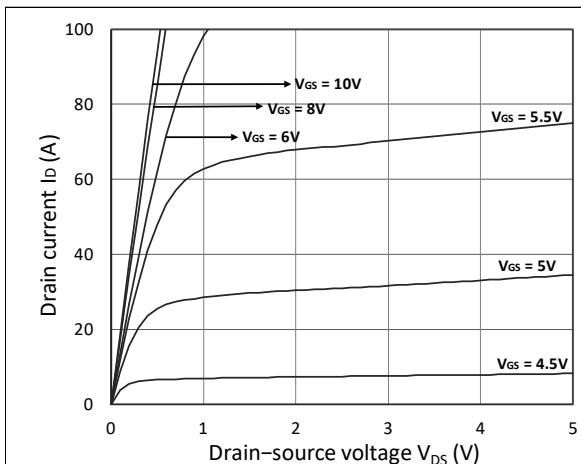


Figure 1. Output Characteristics

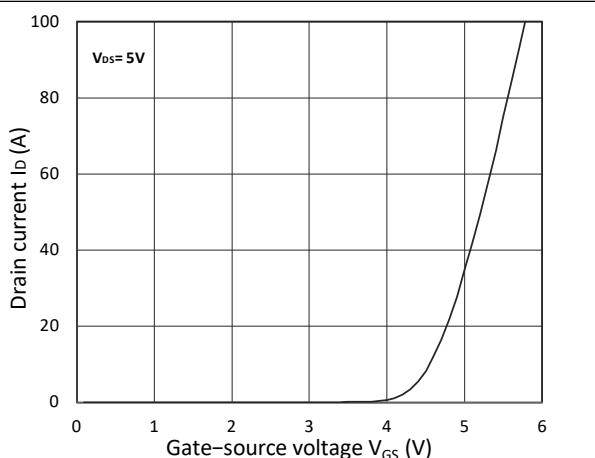


Figure 2. Transfer Characteristics

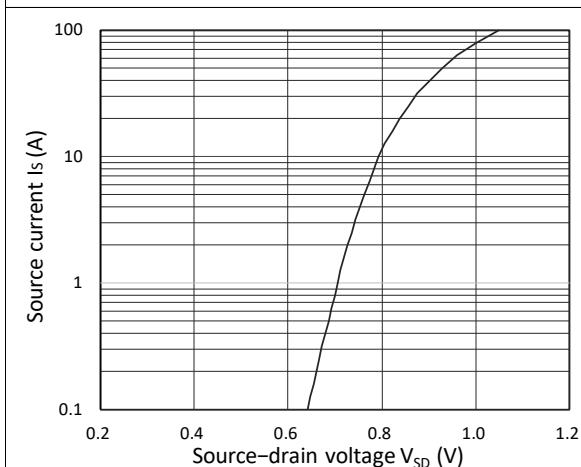
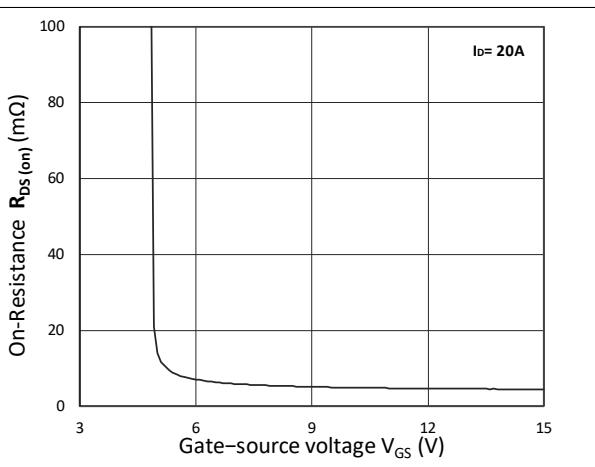
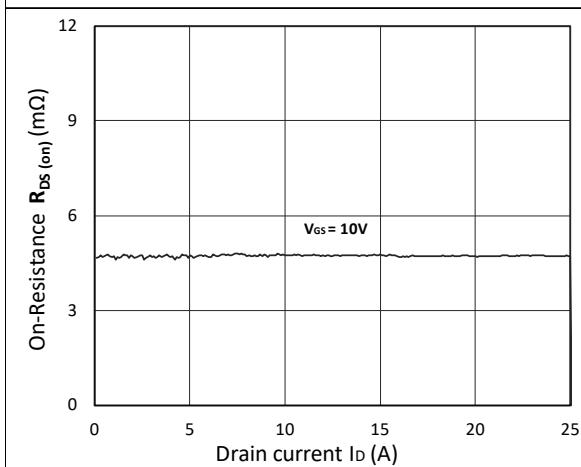
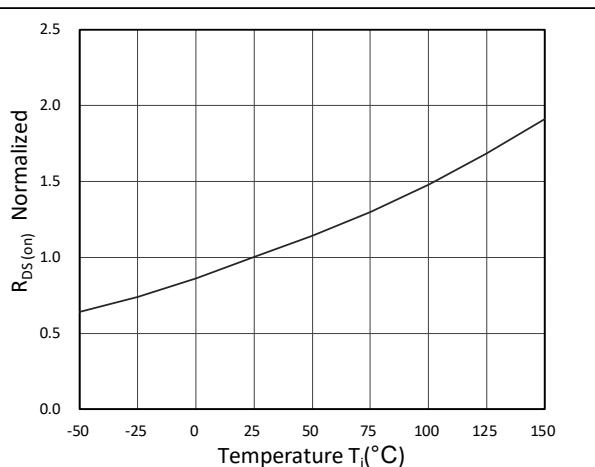
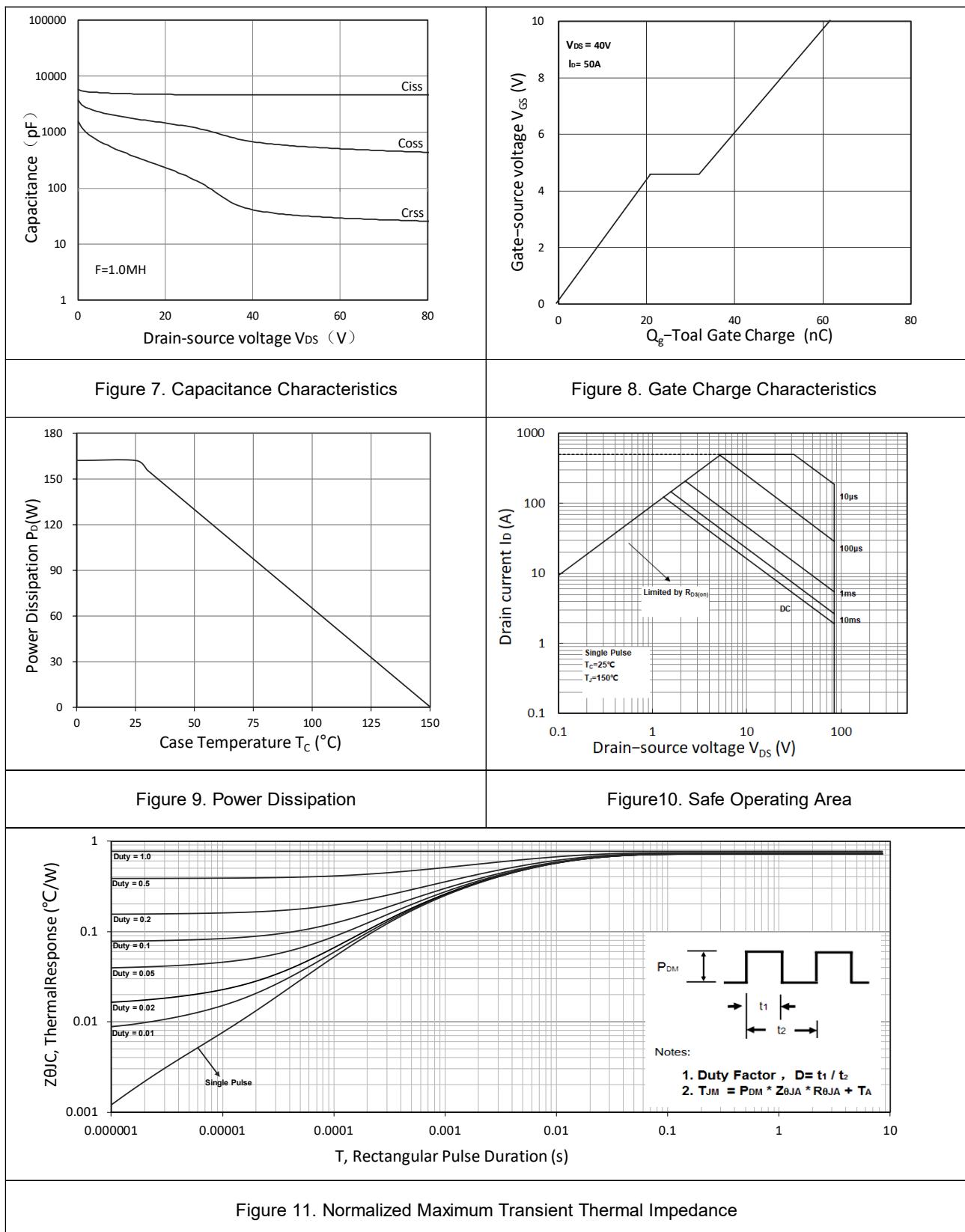
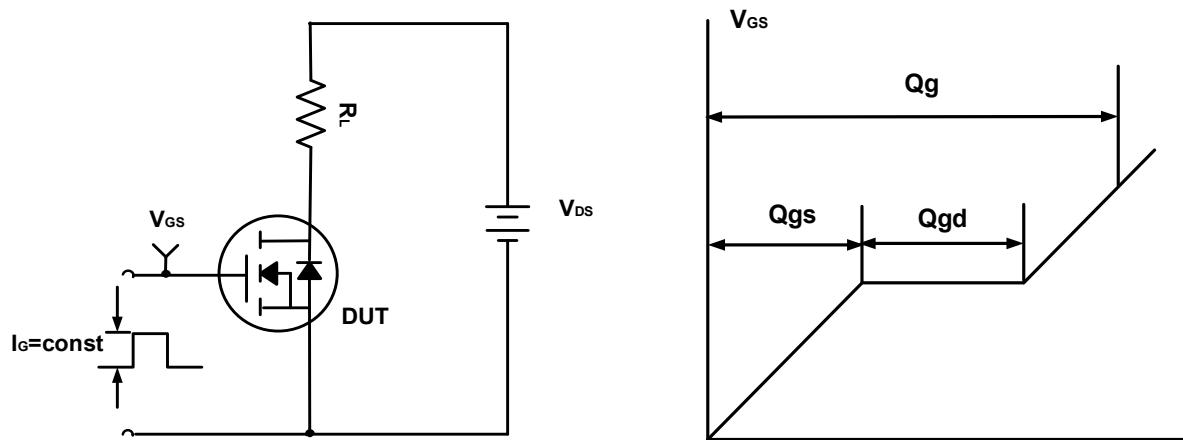
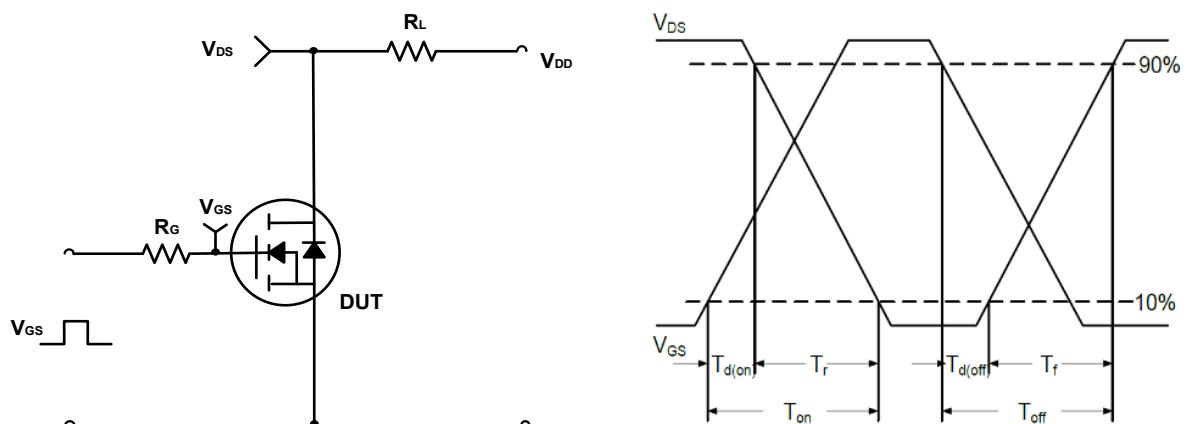
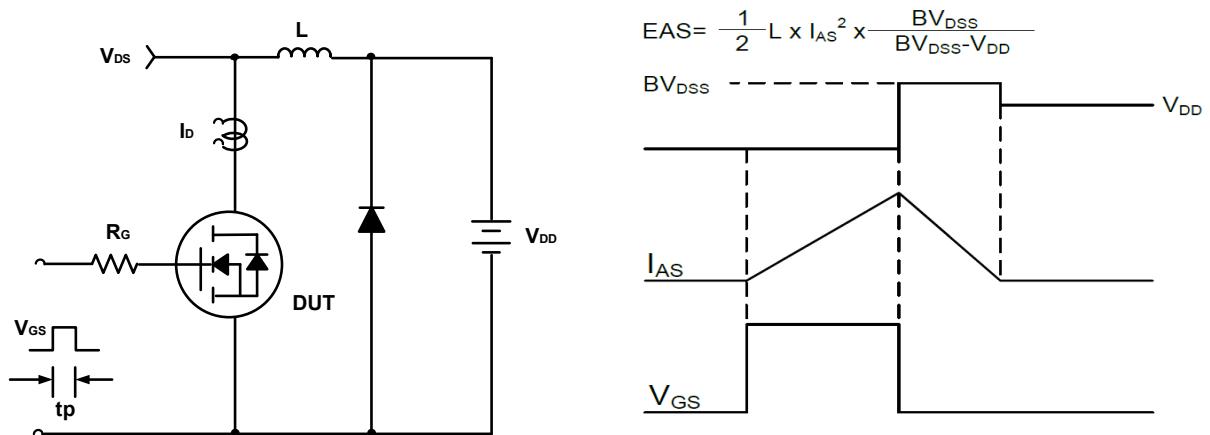


Figure 3. Forward Characteristics of Reverse

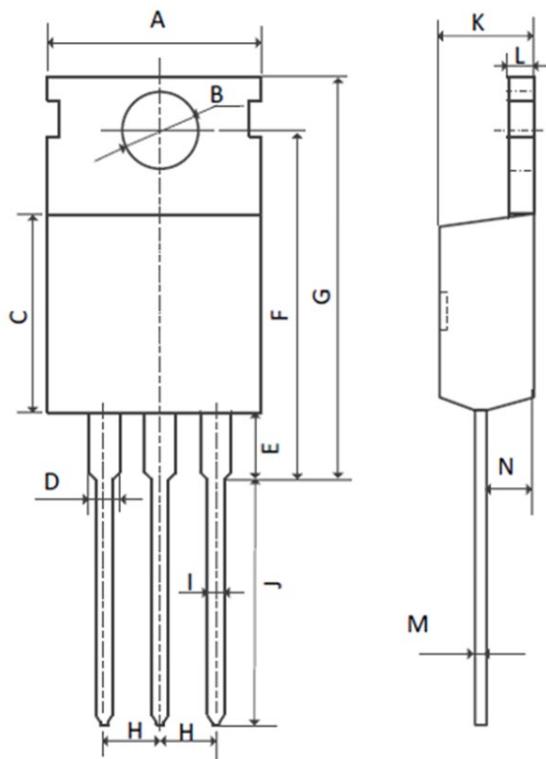
Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature



**Test Circuit****Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## Mechanical Dimensions for TO-220

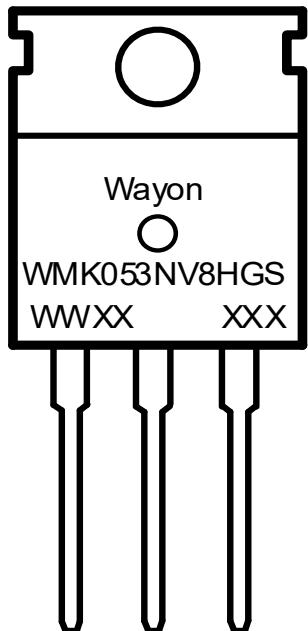
## COMMON DIMENSIONS



SYMBOL	MM	
	MIN	MAX
A	9.70	10.30
B	3.40	3.80
C	8.80	9.40
D	1.17	1.47
E	2.60	3.50
F	15.10	16.70
G	19.55MAX	
H	2.54REF	
I	0.70	0.95
J	9.35	11.00
K	4.30	4.77
L	1.20	1.45
M	0.40	0.65
N	2.20	2.60

**Ordering Information**

Part	Package	Marking	Packing method
WMK053NV8HGS	TO-220	WMK053NV8HGS	Tube

**Marking Information**

WMK053NV8HGS = Device code

WWXX XXX= Date code

**Contact Information**

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WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

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